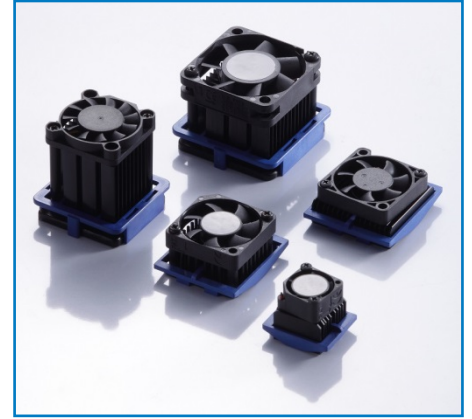


HI-TEMP FAN HEAT SINKS – FHL SERIES

High Operating Temperature Integrated Fan Heat Sinks

DESIGN FEATURES

- Industry-leading maximum operating temperature of 90°C
- Compatible with chipset footprints ranging from 21x21 mm to 45x45 mm
- Total heights from 16.1 mm for low profile applications to 28.1 mm for lowest thermal resistance
- Common 5VDC @ 0.5 A (max) USB 2.0 fan electrical specifications
- Line fin style



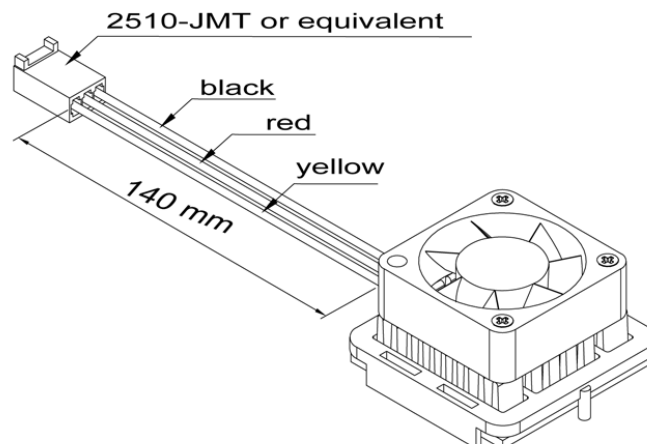
DESCRIPTION

The **FHL** series of integrated-fan heat sinks is uniquely designed to absorb and disperse heat away from high temperature devices while offering key features such as an operating temperature range of -10°C to 90°C, calculated MTTF @ 90°C: 86,858 hours (GEM, 90% confidence) and various package sizes to best fit the application. Thermal resistance values range from 4.07°C/W to as low as 2.52°C/W.

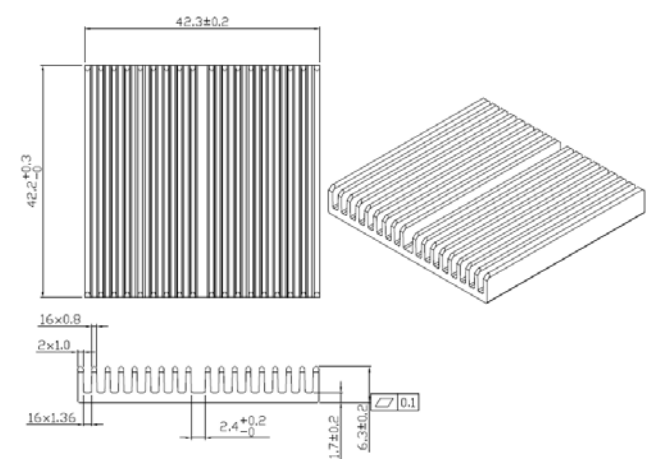
These new fansinks can maintain superior thermal dissipation for devices that emit high amount of heat. CTS' fansinks are available in a wide range of footprints and fin heights which make them suitable for many elevated temperature applications such as component testing, burn-in, high density servers, high- speed computing and video, and use in areas where the system airflow is constrained.

Part Number	Length x Width x Height (mm)	Thermal Resistance (R _{TH})
FHL31-31-17	31 x 31 x 17.0 / 38.1 x 33.6 x 17.0 +/- 0.5 (with clip)	3.01
FHL43-43-17	42.5 x 42.5 x 17.2 / 49.5 x 45.2 x 17.2 +/- 0.5 (with clip)	3.16

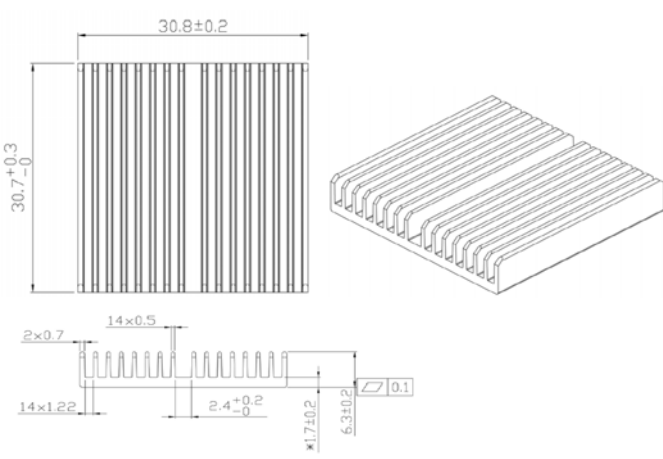
PACKAGE



FHL43-43-17



FHL31-31-17



ORDERING INFORMATION

